



Chapter 4

Metal-Oxide-Semiconductor Field-Effect Transistors (MOSFETs)

Sedra/Smith, Sections 4.1- 4.10, {also 10.3, 6.3}

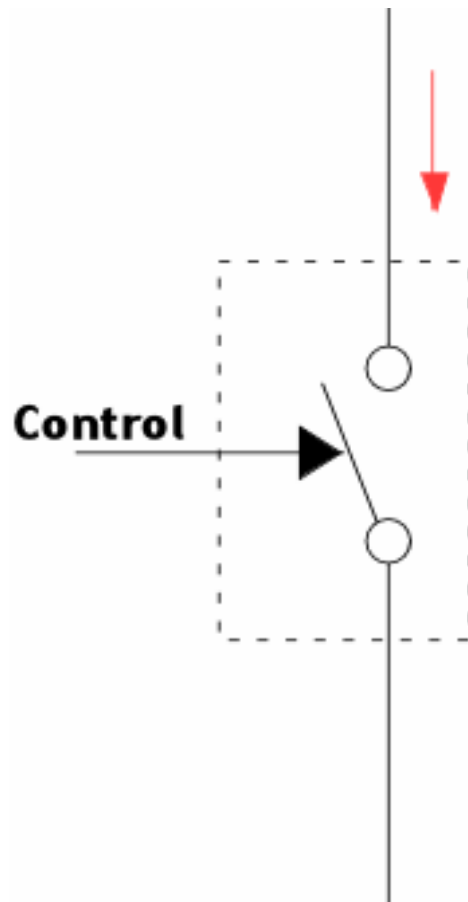


Outline of Chapter 4

- 1- Intro to MOS Field Effect Transistor (MOSFET)
- 2- NMOS FET
- 3- PMOS FET
- 4- DC Analysis of MOSFET Circuits
- 5- MOSFET Amplifier
- 6- MOSFET Small Signal Model
- 7- MOSFET Integrated Circuits
- 8- CSA, CGA, CDA
- 9- CMOS Inverter & MOS Digital Logic



Transistors

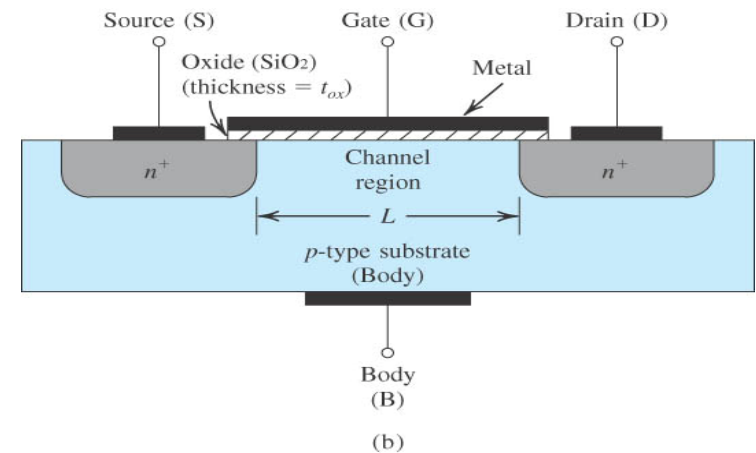
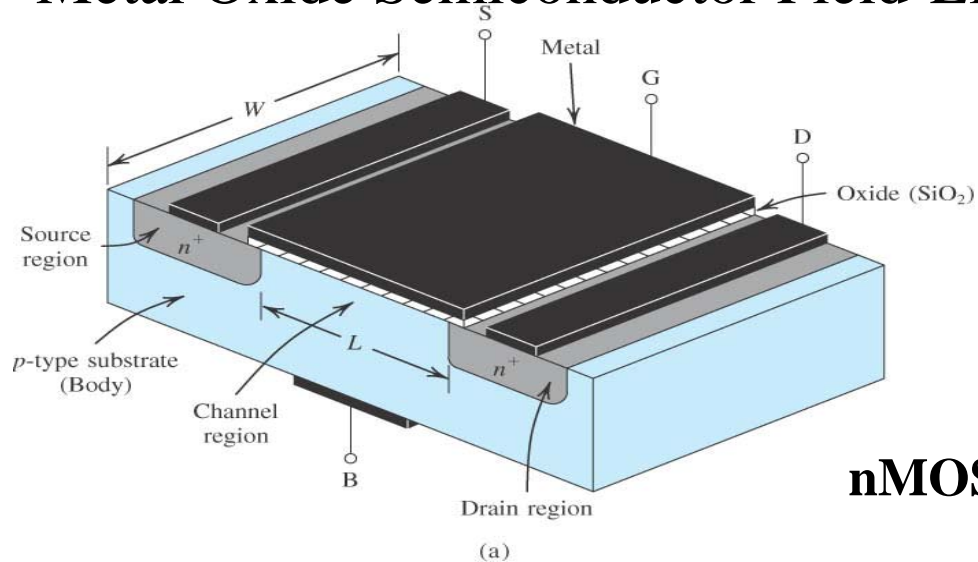


- A *three* terminal device is required to implement current switches and amplifiers.
 - need voltage control terminal
 - used to control current flow through other two terminals
- All four ideal amplifier configurations (Chapter 1) employ **dependent** sources.
- A small control voltage can allow a large change in current.



Transistors-Two PN Junctions

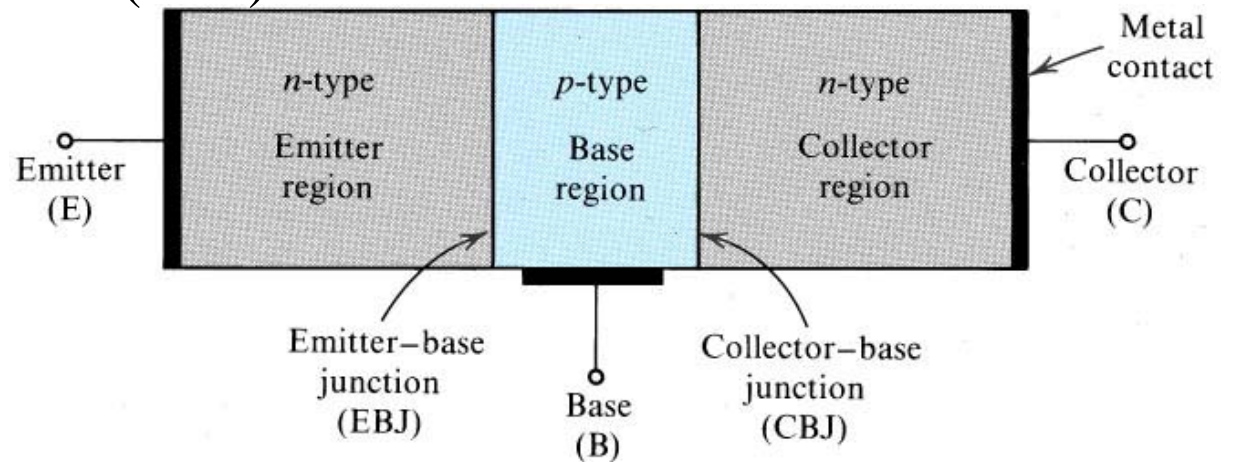
- Metal Oxide Semiconductor Field-Effect Transistors (MOSFET)



nMOS

- Bipolar Junction Transistor (BJT)

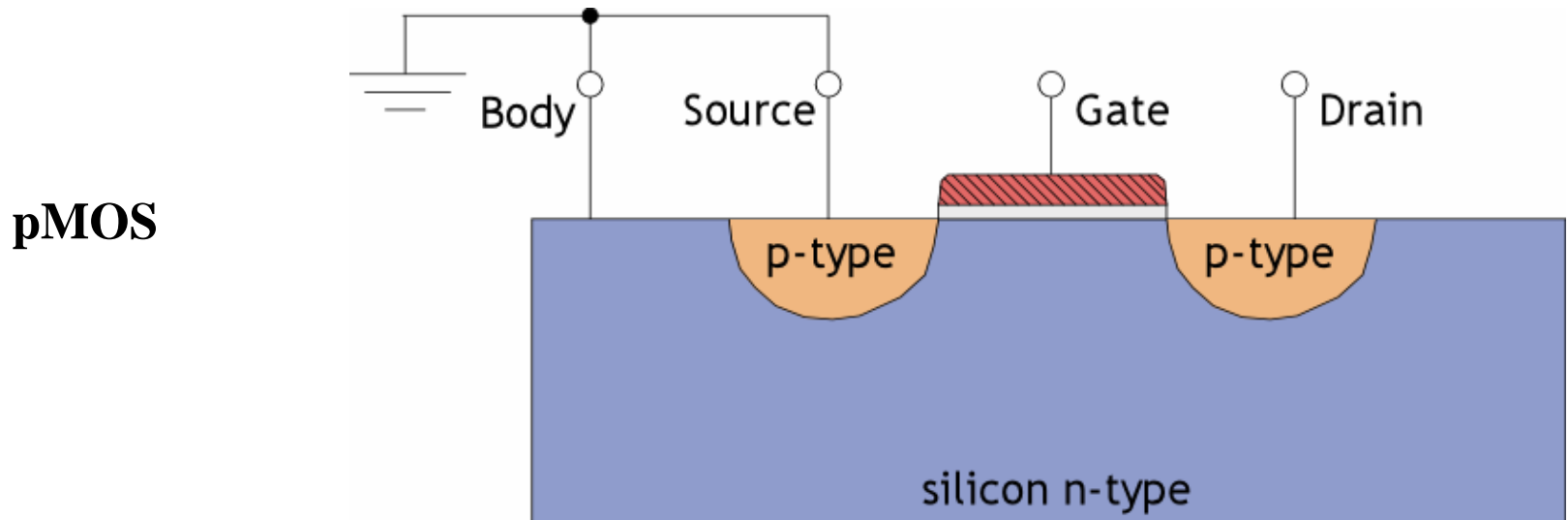
nnp



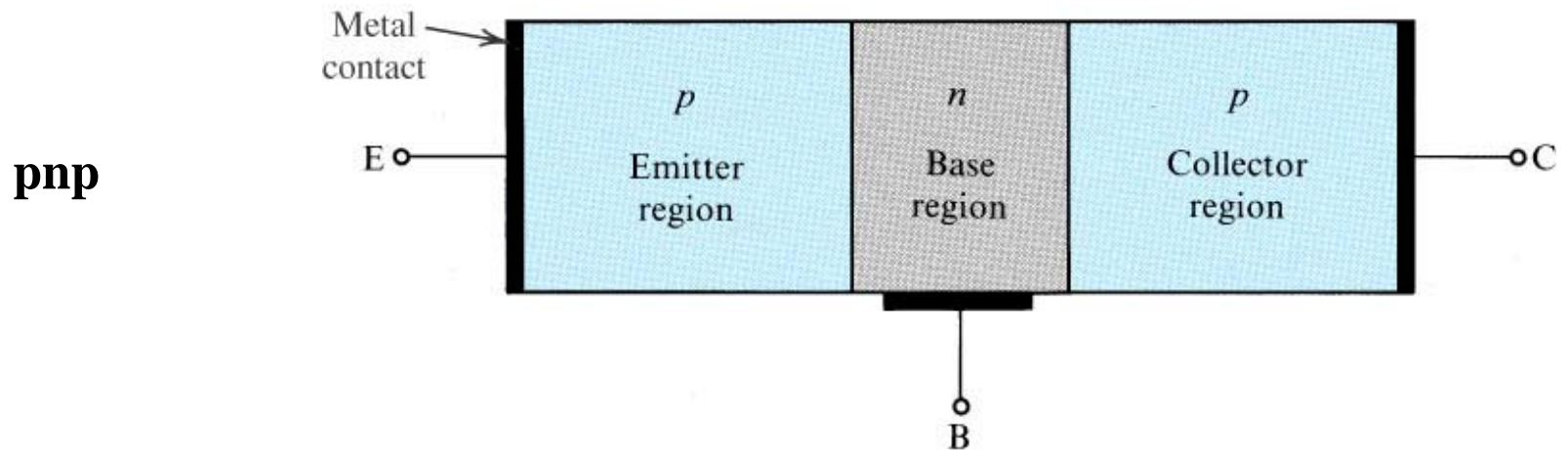


Transistors-Two PN Junctions

- Metal Oxide Semiconductor Field-Effect Transistors (MOSFET)



- Bipolar Junction Transistor (BJT)





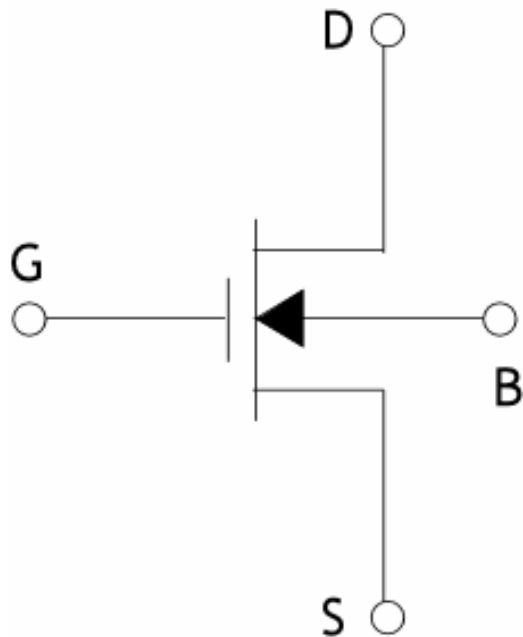
Basic Characteristics of the MOSFET

- The current flows parallel to the surface.
- The MOSFET is usually smaller than the BJT.
 - It consumes less power.
 - It has a much smaller transconductance, g_m , because of its small cross-sectional area.
- Massive integration techniques for digital applications.
- BJTs generally have better performance (predictable small signal parameters).
- Modern digital very-large-scale-integrated (VLSI) circuits employ MOSFETs almost exclusively.
- Analog applications use BJTs only when *top* performance is absolutely essential.

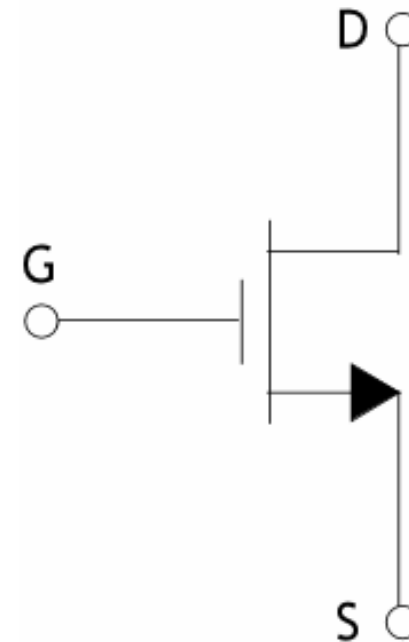


nMOS Circuit Symbol

- A MOSFET is a *four-terminal* device
- Body terminal is *always* biased at *most negative* potential



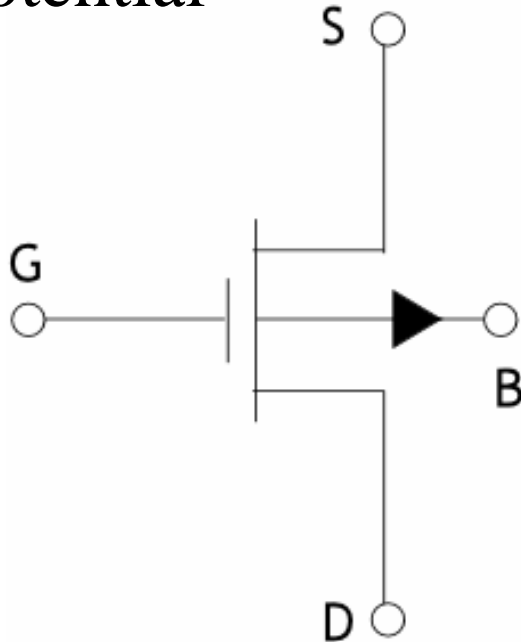
- Simplified symbol with implicit Body terminal connection
- Arrow indicates direction of current



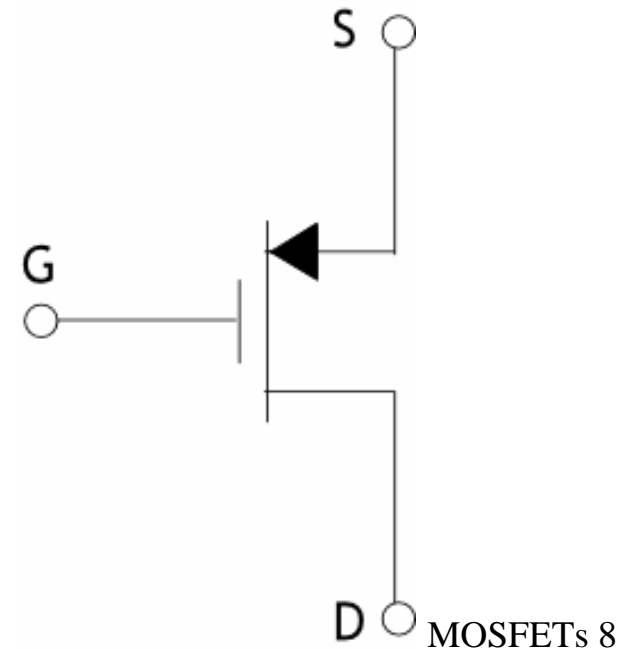


pMOS Circuit Symbol

- A MOSFET is a *four terminal* device
- Body terminal is *always* biased at *most positive* potential

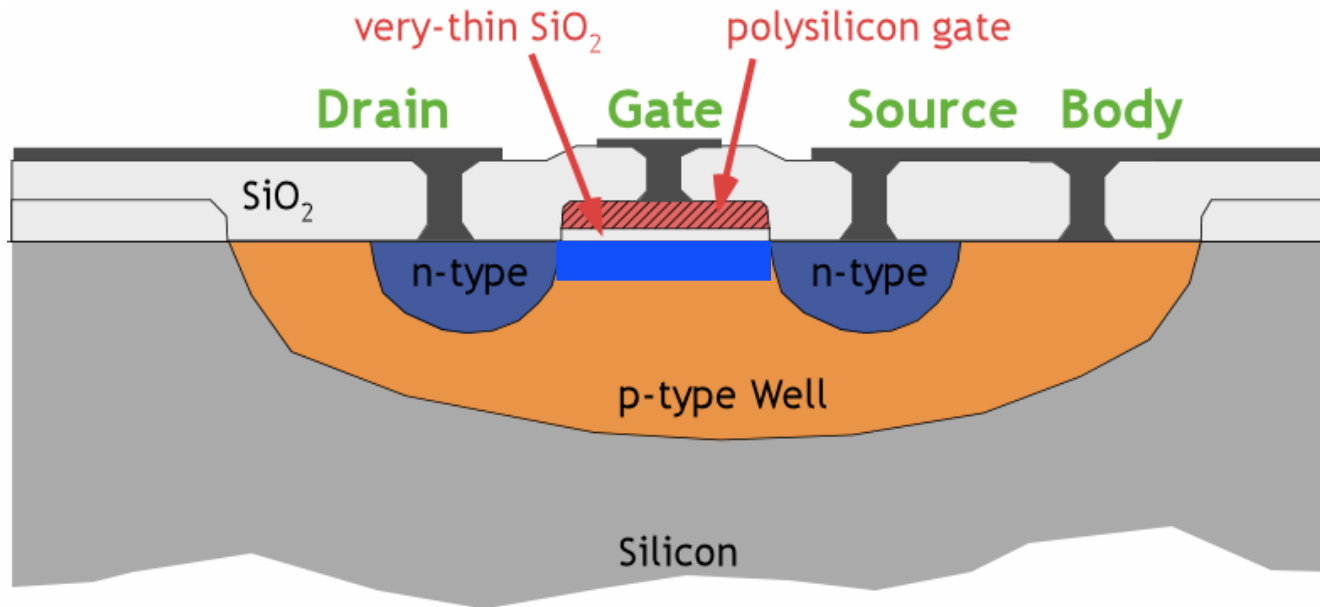


- Simplified symbol with implicit Body terminal connection
- Arrow indicates direction of current flow





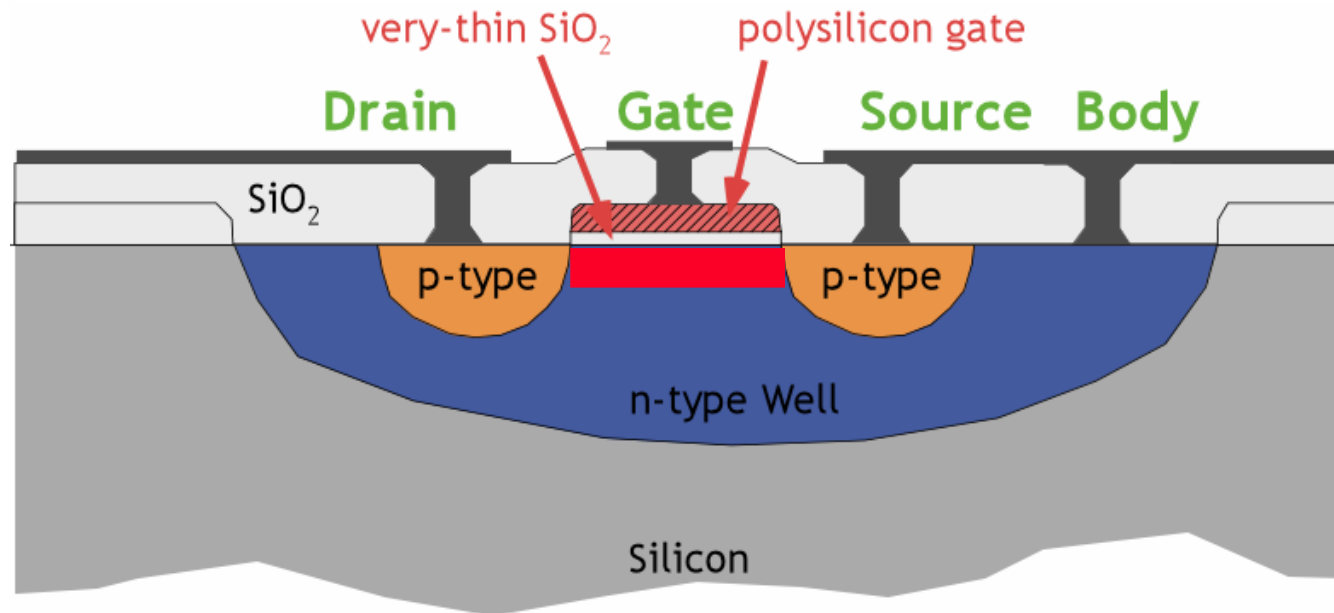
The n-channel MOSFET (nMOS)



- nMOS created in p-type well, this is the **Body**
 - Heavily doped n+ **Drain** and **Source** regions. Usually **Body** and **Source** connected.
 - **Gate** electrode over thin SiO₂ dielectric forms parallel plate capacitor with Body
- This defines the n-channel**



The p-channel MOSFET (pMOS)

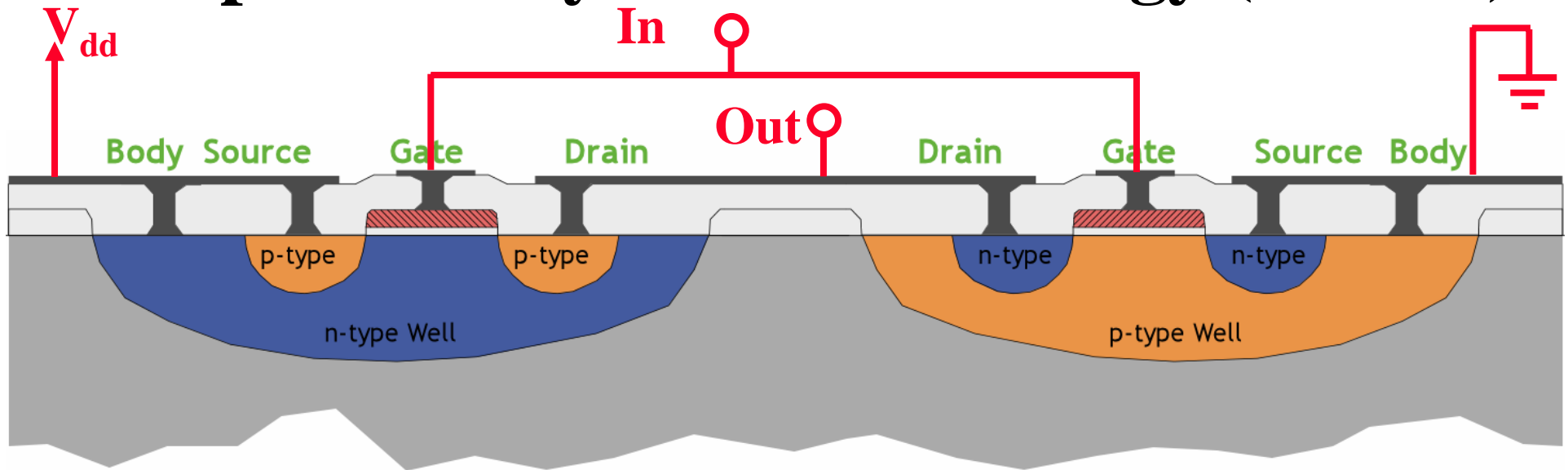


- pMOS created in n-type well, this is the **Body**
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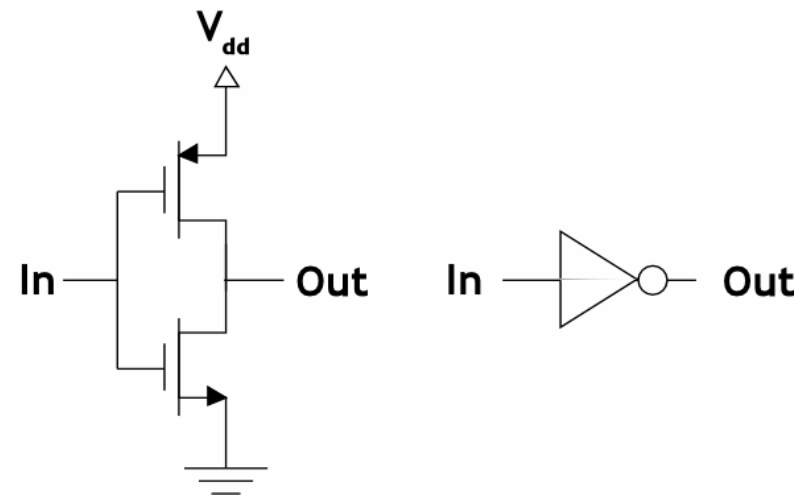
This defines the *p-channel*



Complementary MOS Technology (CMOS)



- CMOS technologies provide nMOS and pMOS devices
- The example shown called dual-well technology.
- p-well *only* and n-well *only* technologies also exist



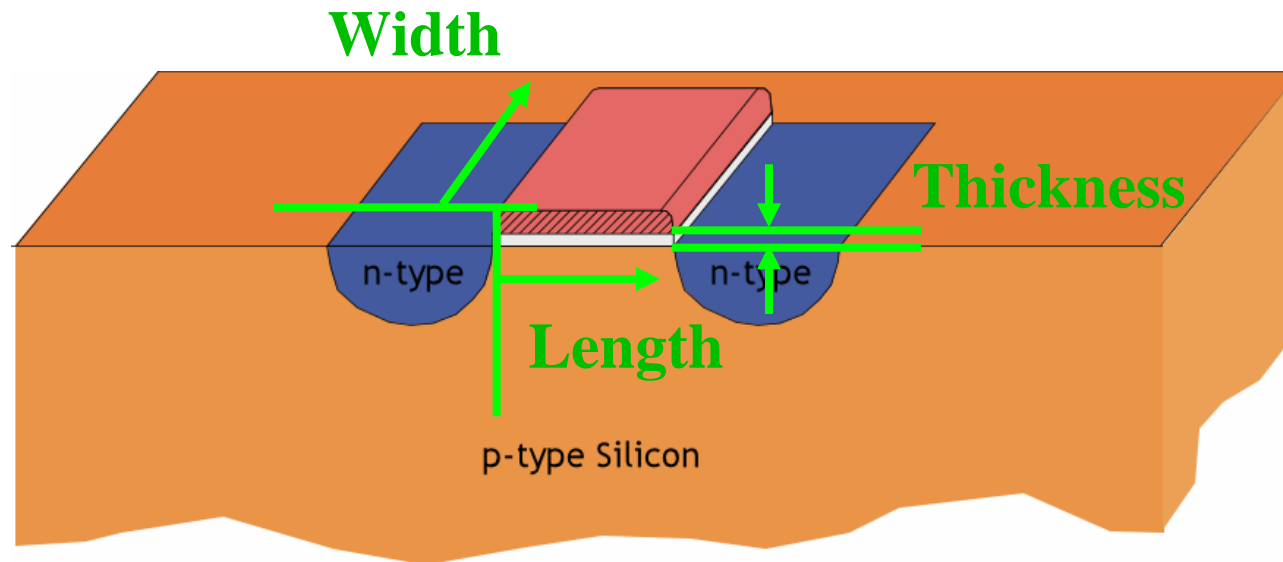


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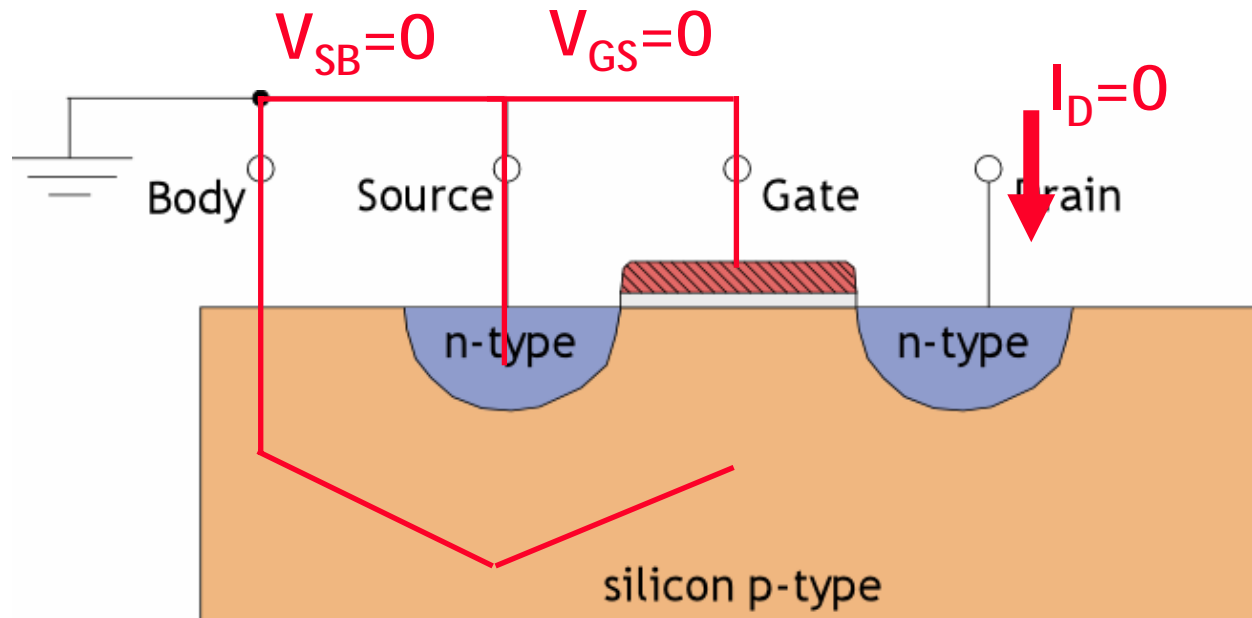
The n-Channel Enhancement MOSFET



- B-S & B-D pn junctions kept reverse-biased with the body terminal the most negative (or attached to the source).
- Aspect ratio of nMOS (W/L) chosen freely, affects g_m .
- Parameters
 - Channel Length (L)
 - Channel Width (W)
 - Oxide Thickness (t_{OX})
 - Oxide permittivity (ϵ_{OX})
 - Electron Mobility (μ_n)



nMOS Channel Cut-off



Cut-Off

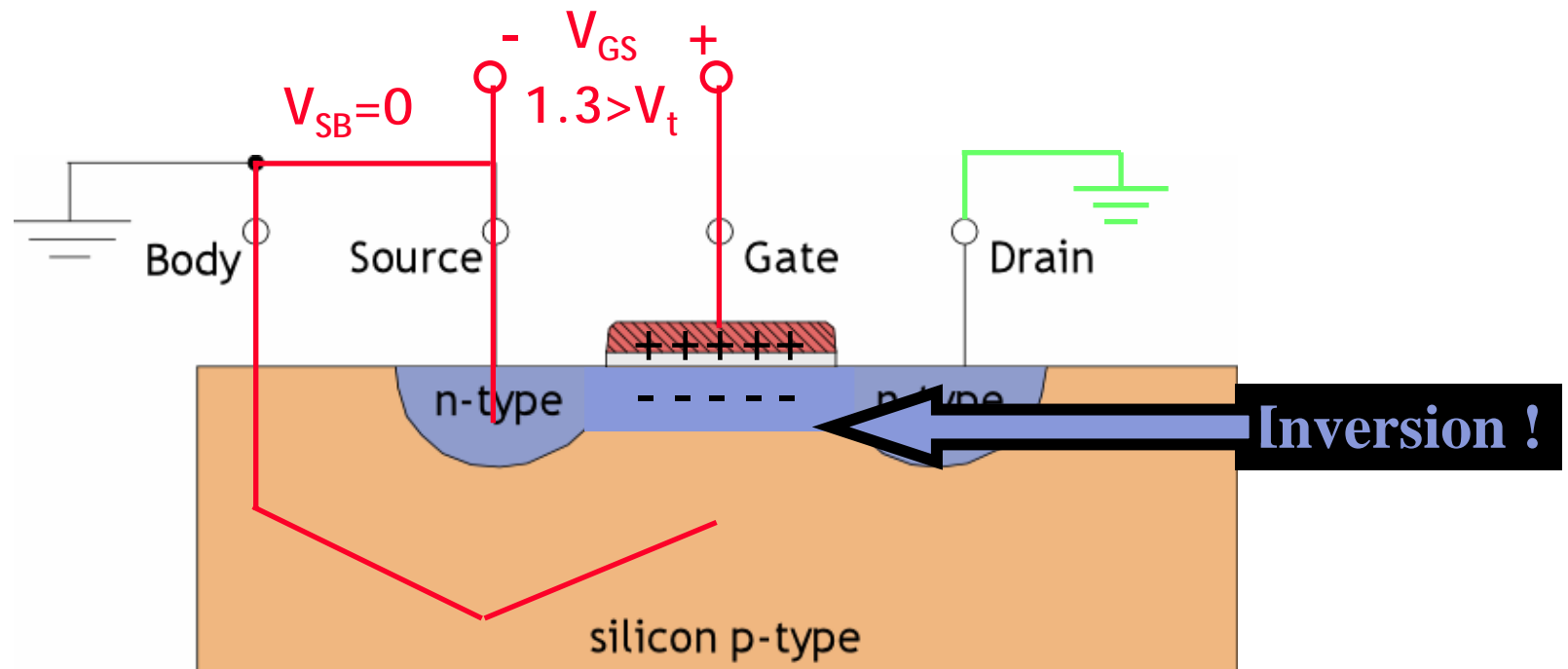
$$V_{GS} < V_t$$

$$I_D = 0$$

- Normally, source & body terminals kept at same potential. ($V_{SB} = 0$)
- When $V_{GS} < V_t = 1V$ (enhancement nMOS) there is **NO** conducting channel. Therefore there can be no movement of charge from drain to source; the current from drain to source, $I_D = 0$.



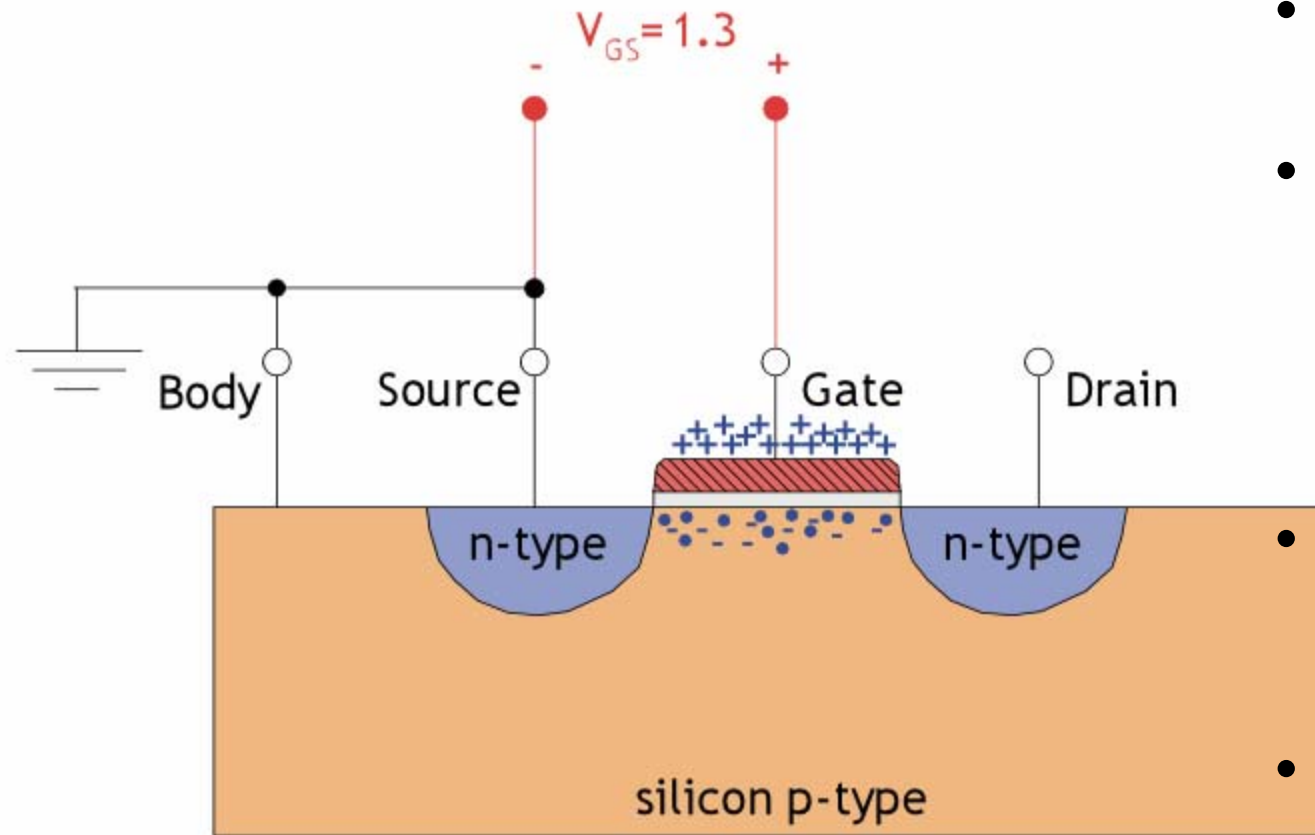
nMOS Channel Conduction



- In order to establish a conducting channel, V_{GS} (V_{GB}) must be made larger than *threshold voltage* V_t . When $V_{GS} > V_t$ (enhancement nMOS) an inversion layer is produced below the gate terminal.
- Channel **conductivity** proportional to $V_{GS} - V_t$ (*excess gate voltage*)



nMOS Channel Inversion Process

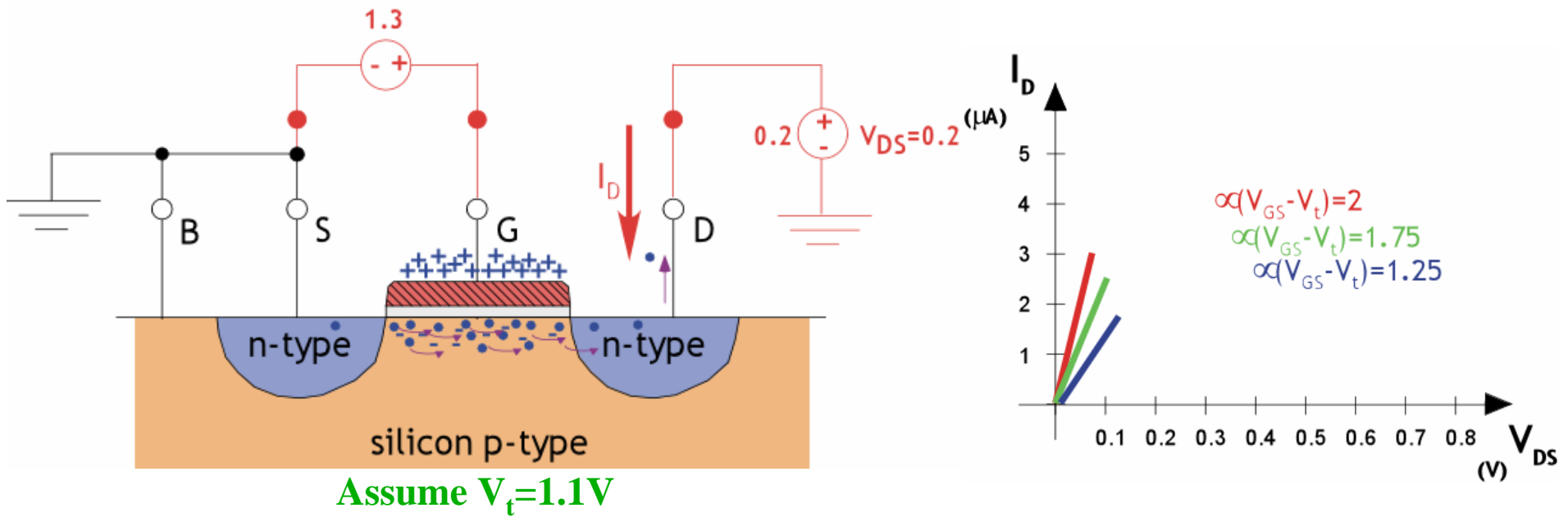


Assume $V_t = 1.1V$

- $V_{GS} = 0$, no channel.
- $V_{GS} = 0.5$, + charges flow onto the gate, repelling holes from surface.
- $V_{GS} = 1.1$ free electrons attracted to surface.
- $V_{GS} = 1.3$, excess free-electrons connect drain and source.



nMOS – Triode

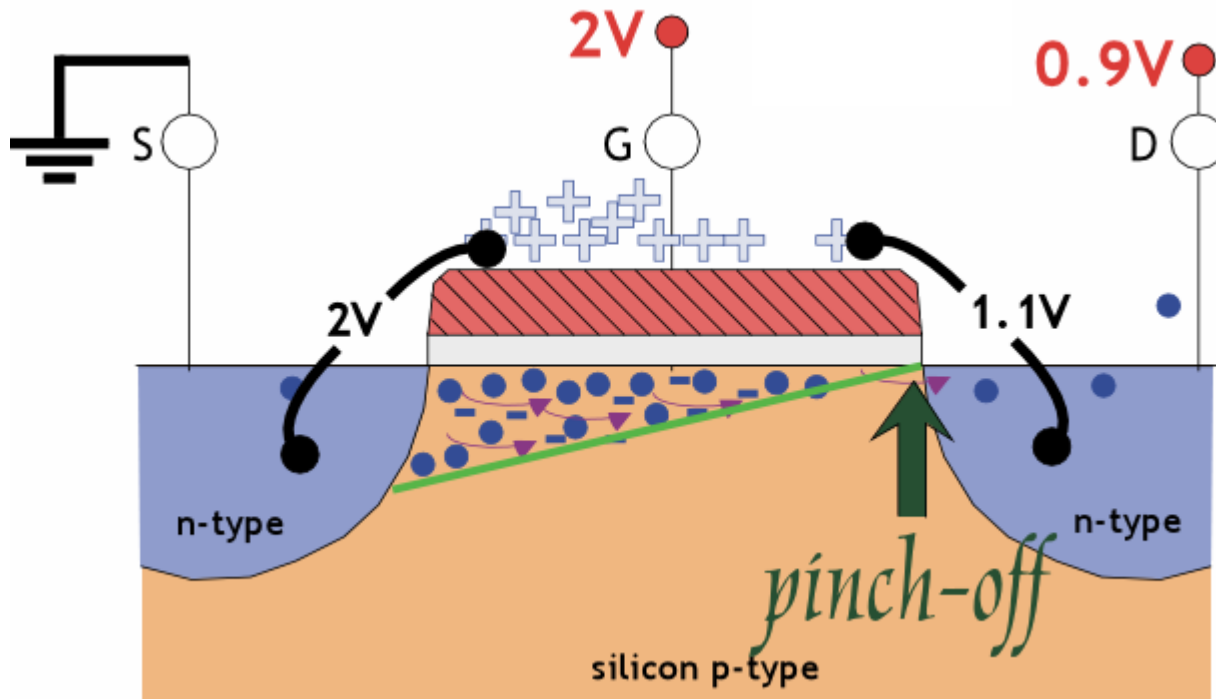


- Once the channel is set-up ($V_{GS} > V_t$), a small voltage between the drain and source, V_{DS} , is applied and current, I_D , begins to flow between drain and source.
- For a *small* V_{DS} :, current is proportional to the amount of inversion ($V_{GS} - V_t$).



nMOS Triode & Pinch-Off

V_{DS} increased, channel shape changes

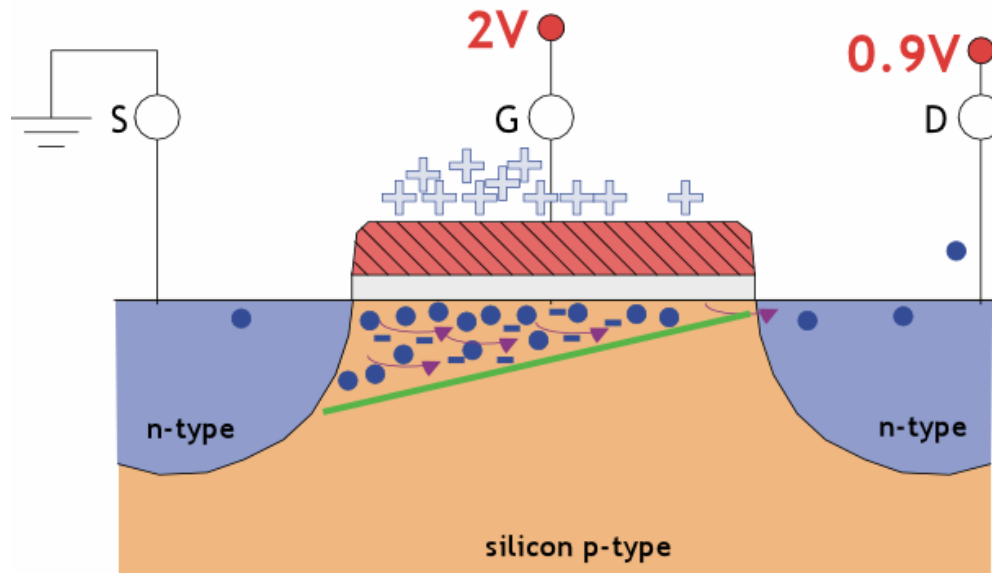


- The channel to source voltage along channel *increases* from V_S at S to $V_S + V_{DS}$ at D.
- The gate to channel voltage *decreases* from V_{GS} at S to $V_{GS} - V_{DS}$ at D.
- Channel shallower at D than S, it has a tapered shape.

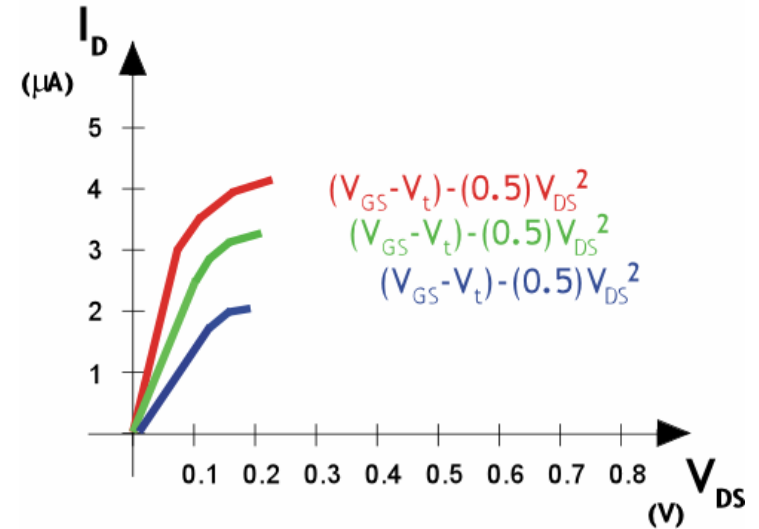
I_D continues to increase up until $V_{GD}=V_t$ at a slower rate



nMOS Triode & Pinch-Off



Assume $V_t = 1.1V$



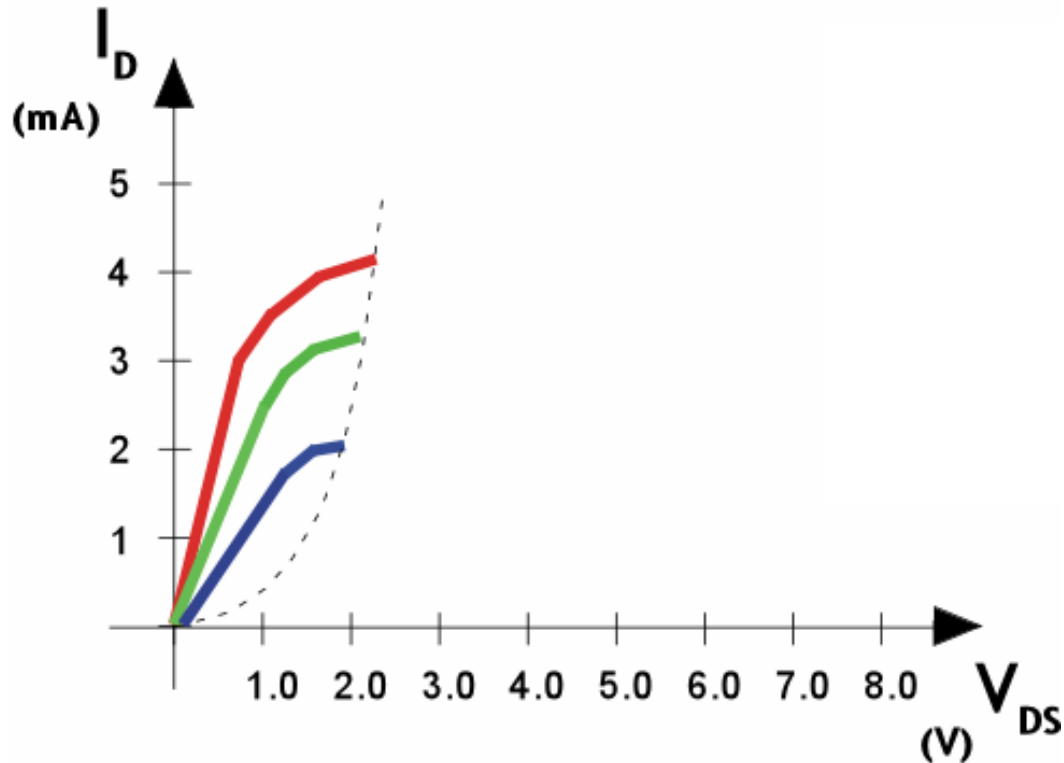
- $V_{DG} = -V_t$ at pinch-off, it is equivalently re-written as:
 $V_{DS} = V_{GS} - V_t$ at pinch-off.
- Triode/saturation boundary:
- Complete triode model includes this decreasing rate of change for I_D .

$$V_{DS} = V_{GS} - V_t$$

$$I_D = k'_n \frac{W}{L} \left[(V_{GS} - V_t) V_{DS} - \frac{1}{2} V_{DS}^2 \right]$$



nMOS Triode– Summary

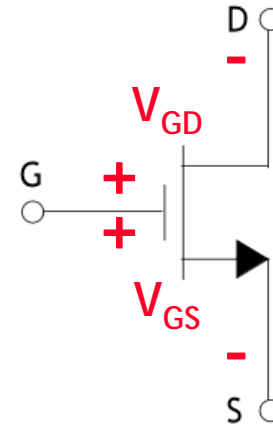


$$I_D = k'_n \frac{W}{L} \left[(V_{GS} - V_t) V_{DS} - \frac{1}{2} V_{DS}^2 \right]$$

$$k'_n = \mu_n \frac{\epsilon_{ox}}{t_{ox}}$$

$$V_{DS} < V_{GS} - V_t$$

$$V_{GS} > V_t$$



Triode Example:
 $V_{GS} > V_t$, and $V_{GD} > V_t$

If $V_t = 1.1V$

$V_{GS} = 3.2V$

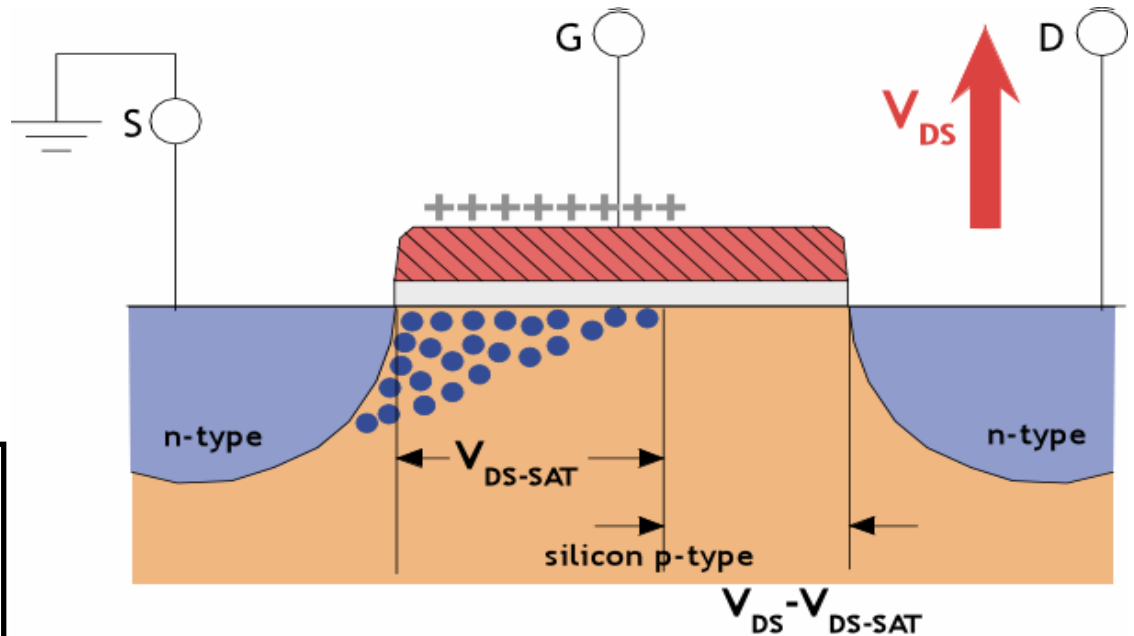
$V_{GD} = 2.2V$

And $V_{DS} = 1.0V$



nMOS – Saturation

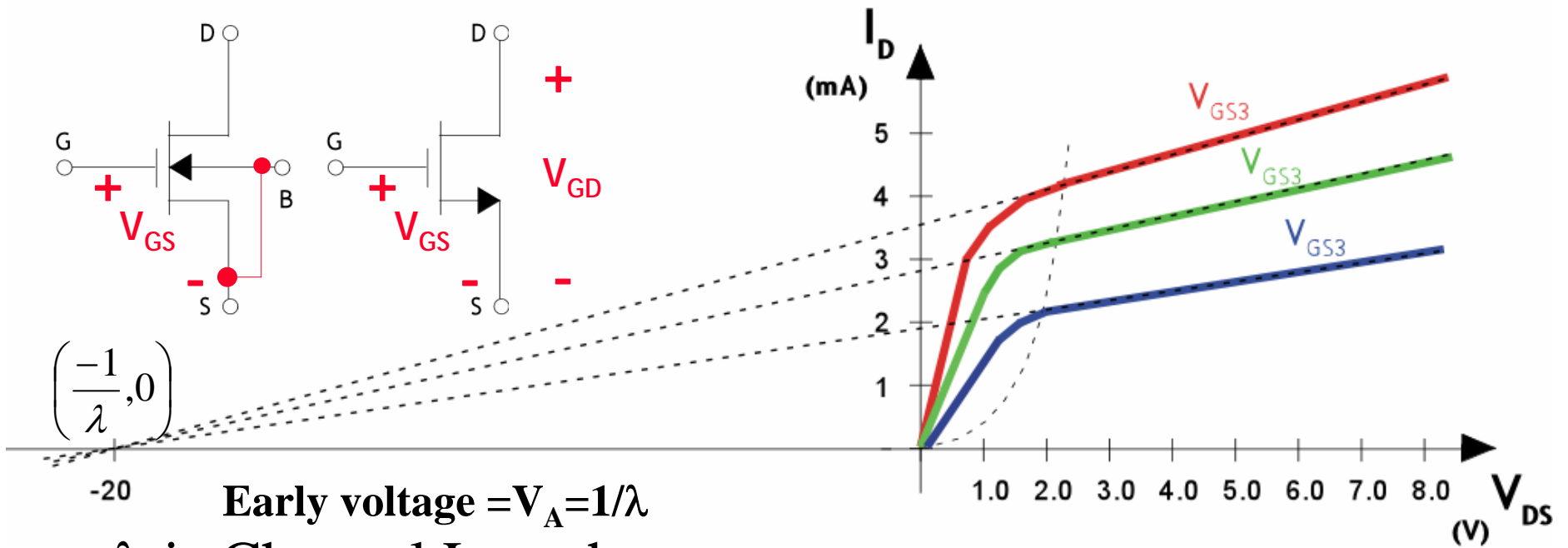
- Once channel pinch-off reached ($V_{DS} = V_{DS-SAT}$), nMOS enters saturation.
- As V_{DS} is further increased, the edge near the drain completely loses inversion and the inversion/pinch-off point starts to move towards the source.
- To first-order, I_D doesn't change:
 - The voltage from the source up to the pinch-off point is V_{DS-SAT}
 - And the excess voltage ($V_{DS} - V_{DS-SAT}$) is across the rest of the channel.



$$I_D = \frac{1}{2} k'_n \frac{W}{L} (V_{GS} - V_t)^2$$



nMOS Saturation – Summary



- λ is Channel Length Modulation parameter
- Typically 0.005-0.05 V^{-1}

$$I_D = \frac{1}{2} k'_n \frac{W}{L} (V_{GS} - V_t)^2 (1 + \lambda V_{DS})$$

$$k'_n = \mu_n \frac{\epsilon_{ox}}{t_{ox}}$$

$$V_{DS} \geq V_{GS} - V_t$$

$$V_{GS} > V_t$$

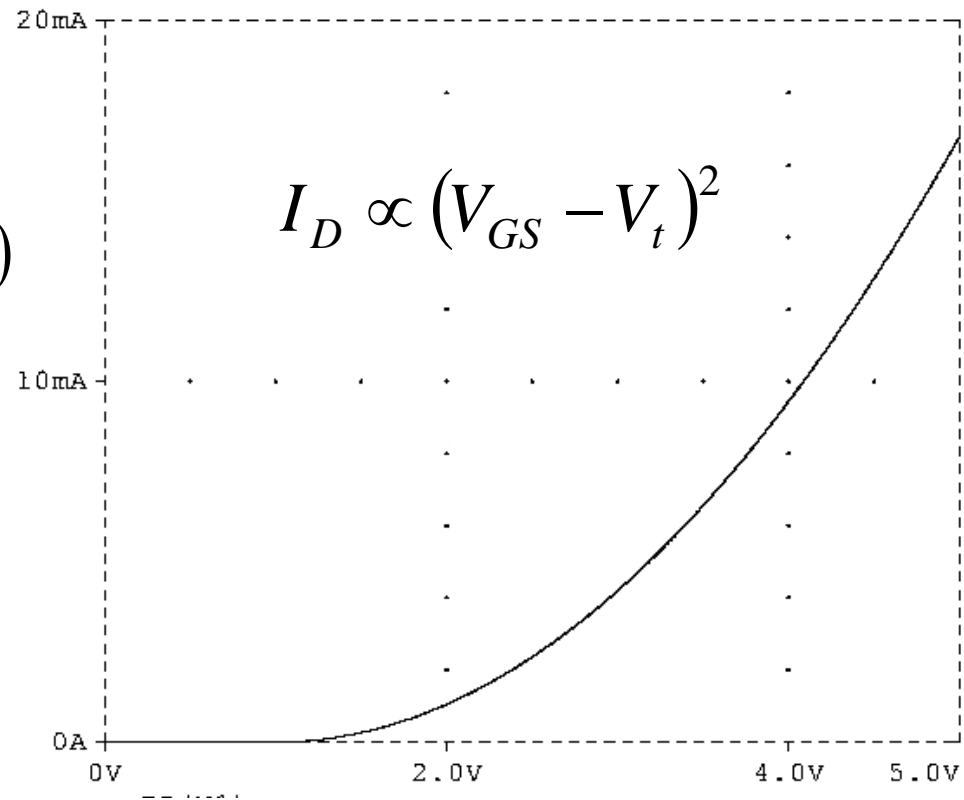


nMOS Saturation – I_D vs V_{GS} Curve

- For constant V_{DS} , I_D vs V_{GS} is quadratic

$$I_D = \frac{1}{2} k'_n \frac{W}{L} (V_{GS} - V_t)^2 (1 + \lambda V_{DS})$$

- We will see that this is analogous to I_C vs V_{BE} curve for a BJT
- MOSFET is less non-linear compared to a BJT

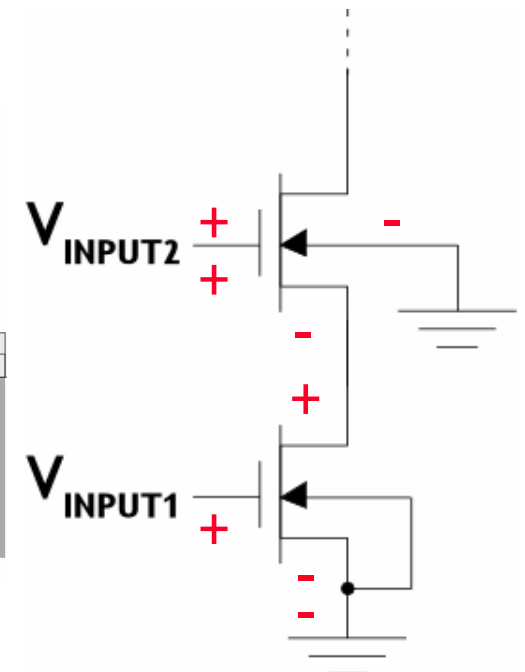
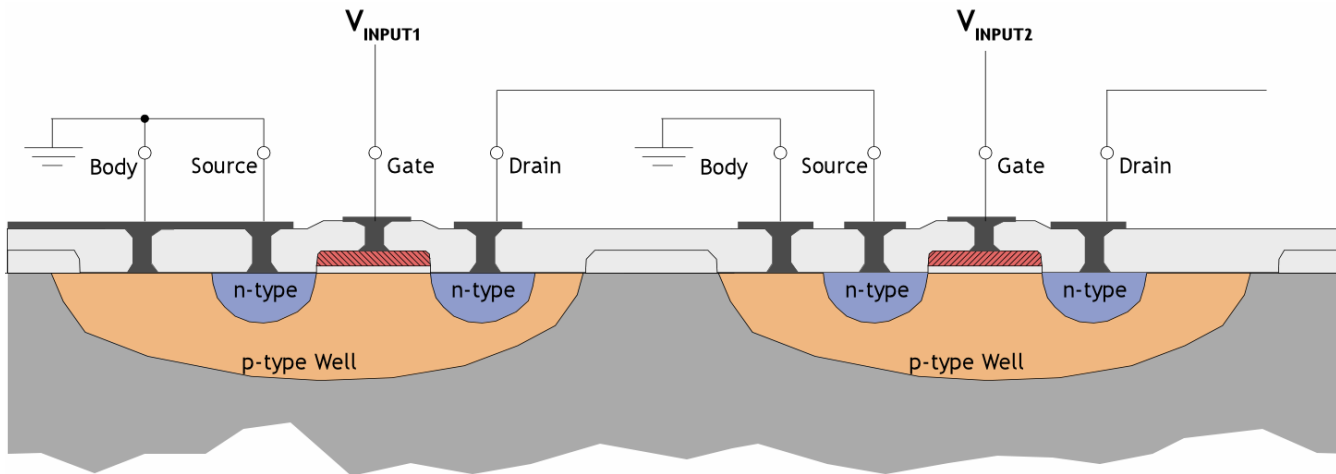




nMOS – The Body Effect

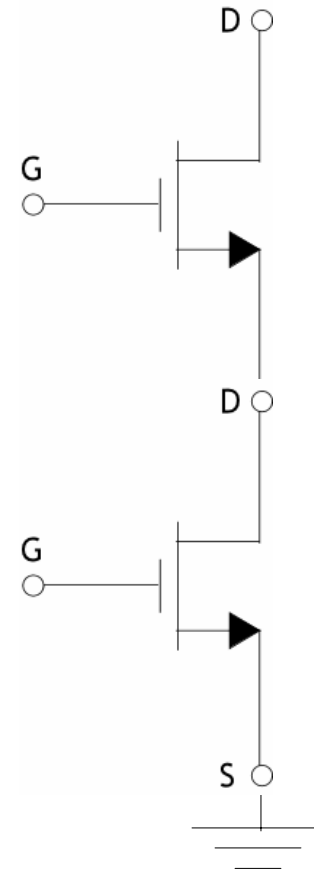
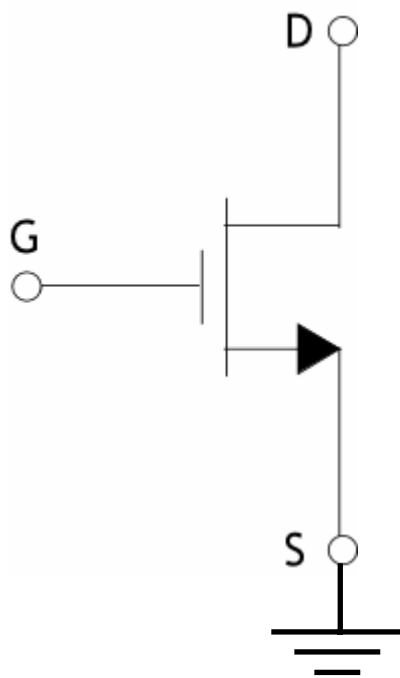
- It is not always possible to keep source and body at same potential:
 - $V_{SB} \neq 0$ accounted for in V_t
 - γ : Body effect parameter, typically $0.5V^{1/2}$
 - $2\phi_f$: Surface potential, equal to $\sim 0.6V$
 - V_{t0} : threshold when $V_{SB} = 0$

$$V_t = V_{t0} + \gamma \left(\sqrt{2\phi_f + V_{SB}} - \sqrt{2\phi_f} \right)$$





The Body Effect





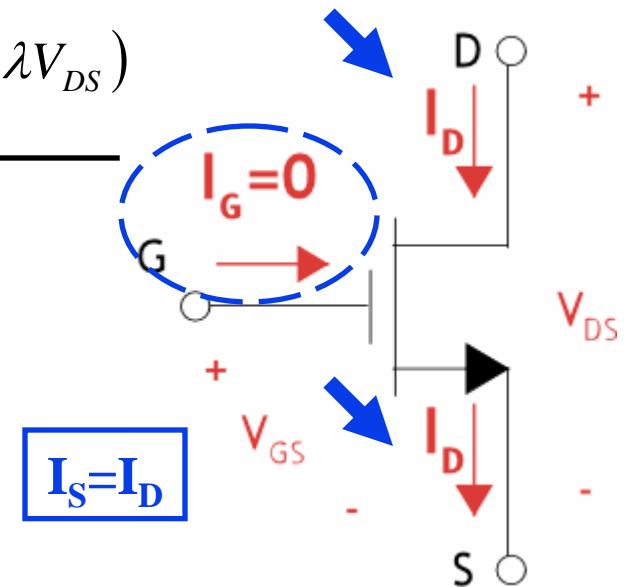
Summary of Enhancement nMOS FET I-V Characteristics

Cutoff: $V_{GS} < V_t$ $I_D = 0$

Triode: $V_{GS} > V_t$
 $V_{DS} < V_{GS} - V_t$ $I_D = k'_n \frac{W}{L} \left[(V_{GS} - V_t)V_{DS} - \frac{1}{2}V_{DS}^2 \right]$

Saturation: $V_{GS} > V_t$
 $V_{DS} > V_{GS} - V_t$ $I_D = \frac{1}{2}k'_n \frac{W}{L} (V_{GS} - V_t)^2 (1 + \lambda V_{DS})$

Body effect: $V_t = V_{t0} + \gamma \left(\sqrt{2\phi_f + V_{SB}} - \sqrt{2\phi_f} \right)$





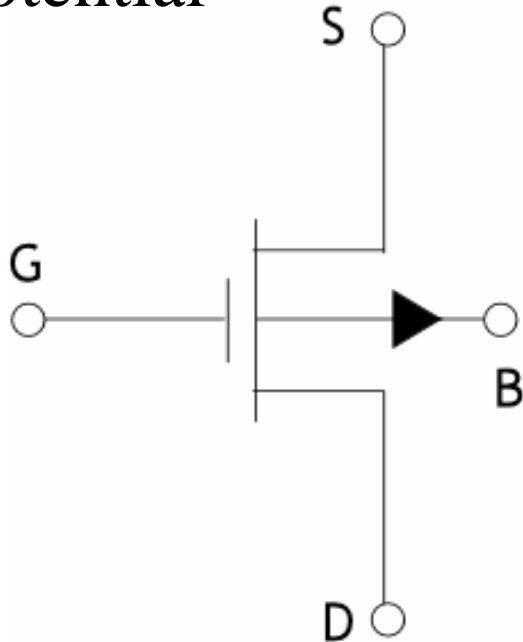
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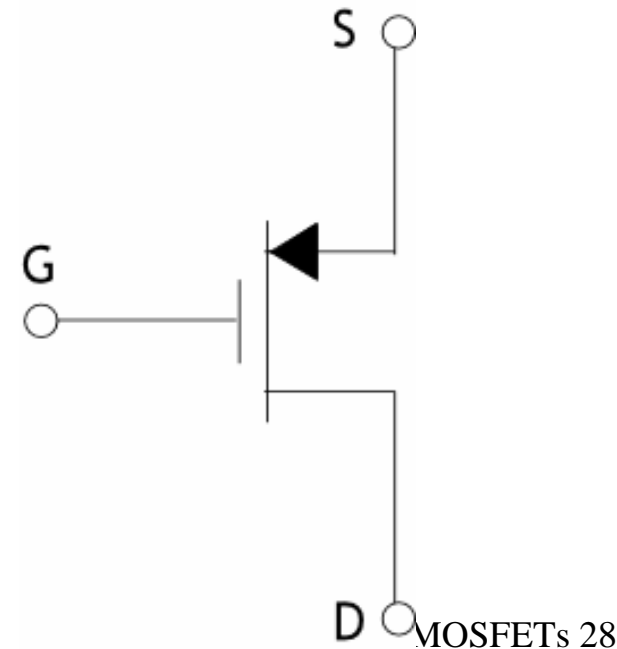


pMOS Circuit Symbol

- A MOSFET is a *four terminal* device
- Body terminal *always* biased at *most positive* potential

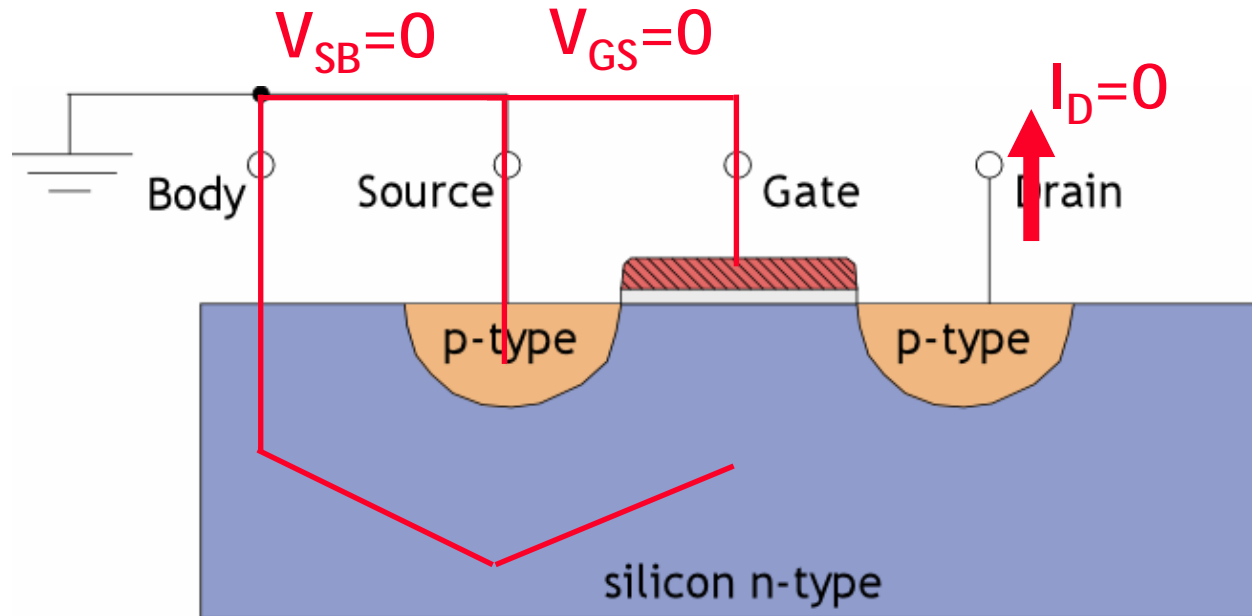


- Simplified symbol with implicit Body terminal connection
- Arrow indicates direction of current flow





pMOS Channel Cut-off



Cut-Off

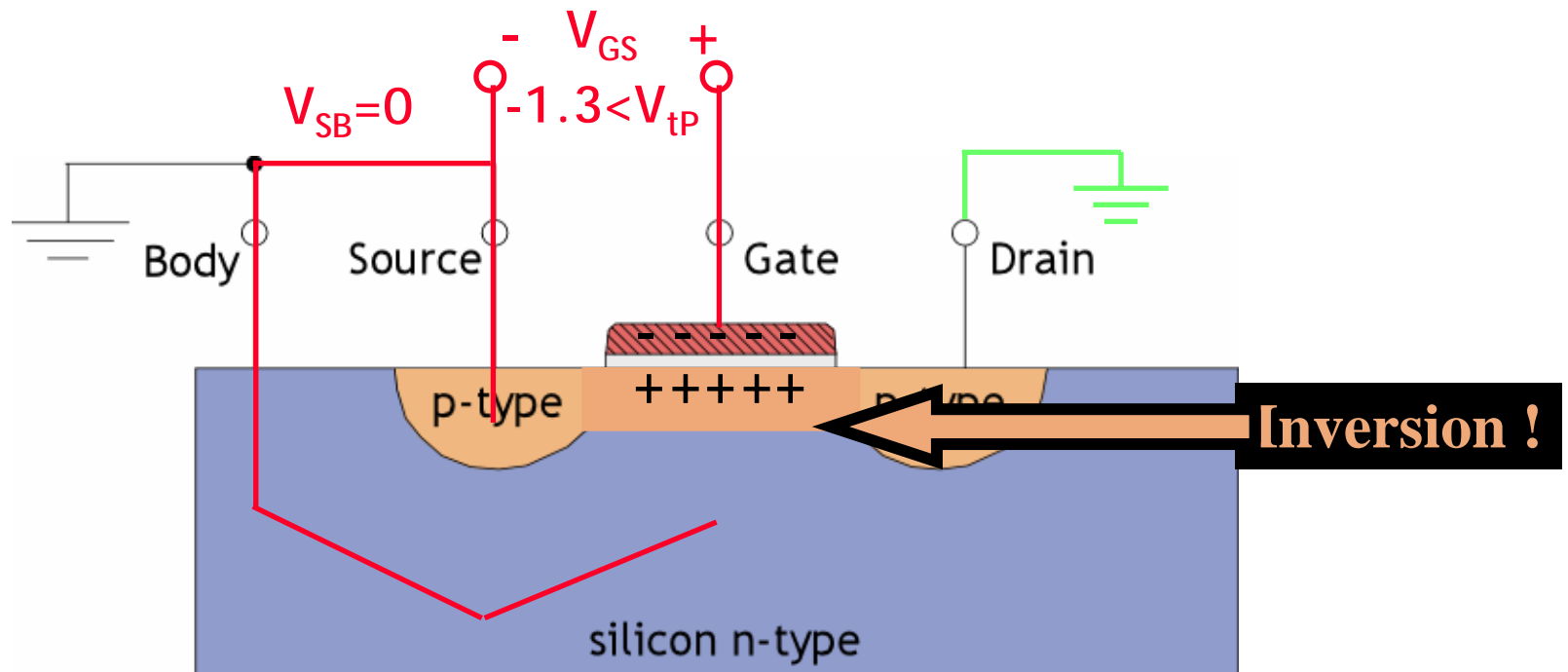
$$V_{GS} > V_{tP}$$

$$I_D = 0$$

- Source & body terminals are kept at same potential. ($V_{SB} = 0$)
- When $V_{GS} > V_{tP} = -1V$ (enhancement pMOS) there is **NO** conducting channel. Therefore there can be no movement of charge from drain to source; the current from drain to source, $I_D = 0$.



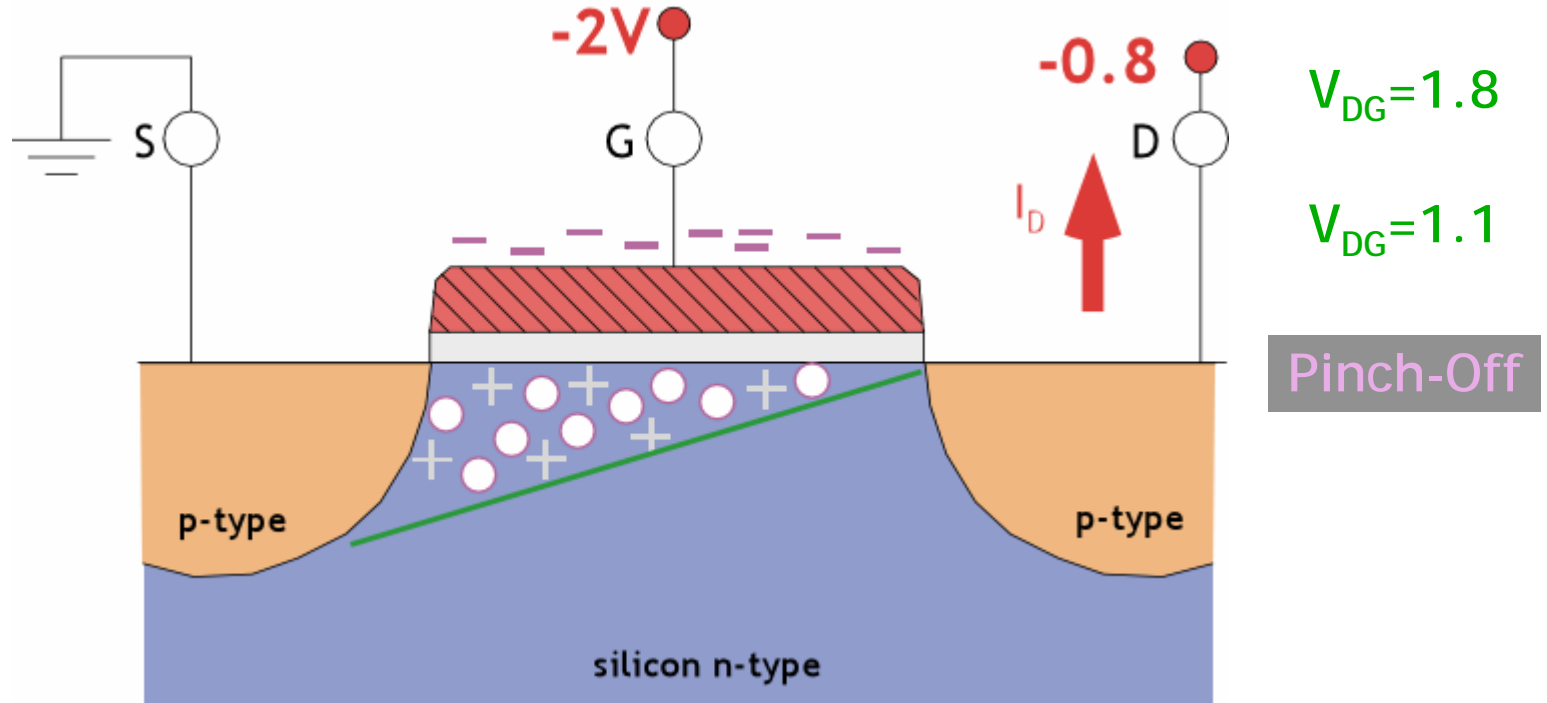
pMOS Channel Conduction



- To establish a conducting channel, V_{GS} (V_{GB}) must be made smaller than *threshold voltage* V_{tp} . When $V_{GS} < V_{tp} = -1V$ (enhancement pMOS) an inversion layer is produced below the gate terminal.
- Channel **conductivity** proportional to $V_{GS} - V_{tp}$ (*excess gate voltage*)



pMOS Triode Region



$$V_{DG} = 1.8$$

$$V_{DG} = 1.1$$

Pinch-Off

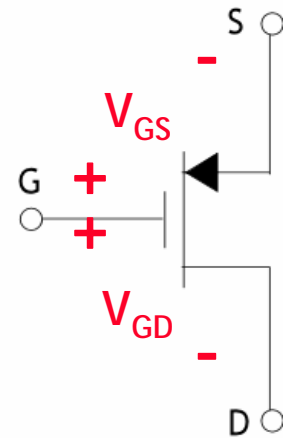
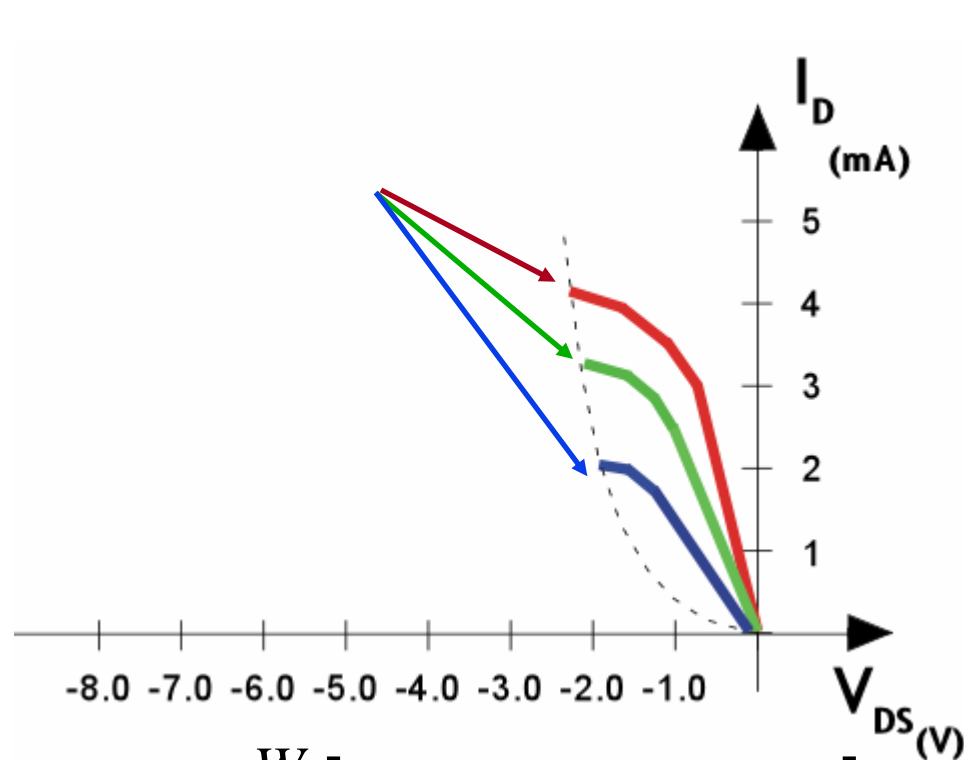
Assume $V_{tP} = -1.1V$

- If $V_{DG} = -V_t$, at pinch-off, then re-written: $V_{DS} = V_{GS} - V_{tP}$ at pinch-off.

$$V_{DS} = V_{GS} - V_{tP}$$



pMOS Triode Region – Summary



Triode Example:
 $V_{GS} < V_t$, and $V_{GD} < V_t$

If $V_t = -1.1V$

$V_{GS} = -3.2V$

$V_{GD} = -2.2V$

And $V_{DS} = -1.0V$

$$I_D = k'_p \frac{W}{L} \left[(V_{GS} - V_t) V_{DS} - \frac{1}{2} V_{DS}^2 \right]$$

$$k'_p = \mu_p \frac{\epsilon_{ox}}{t_{ox}}$$

$$V_{GS} < V_t$$

$$V_{DS} > V_{GS} - V_t$$

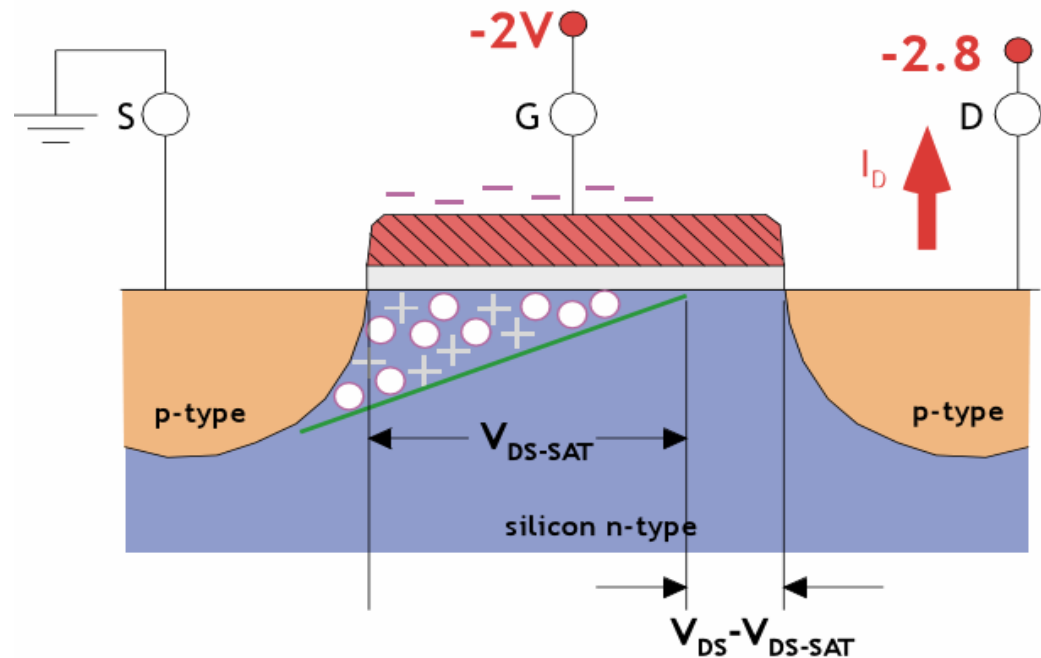


pMOS – Saturation

- Once channel pinch-off is reached ($V_{DS} = V_{DS-SAT}$), the pMOS enters saturation mode.
- As V_{DS} is further decreased, the edge near the drain completely loses inversion and the inversion/pinch-off point starts to move towards the source.

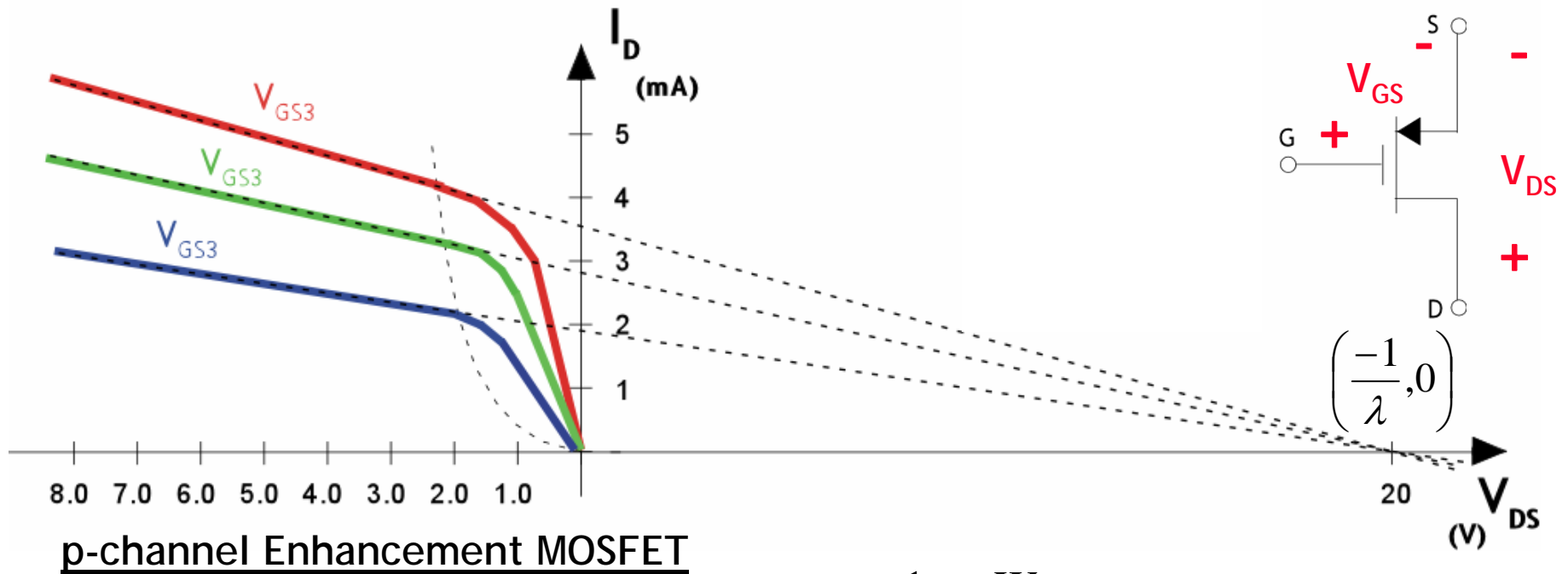
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 - The voltage from the source up to the pinch-off point is V_{DS-SAT}
 - The excess voltage ($V_{DS} - V_{DS-SAT}$) is across the rest of the channel.

$$I_D = \frac{1}{2} k'_p \frac{W}{L} (V_{GS} - V_t)^2$$





pMOS Saturation – Summary



- λ is CLM parameter
- λ is negative
 - typically -0.005 to -0.05 V^{-1}
 - Extrapolated curves intersect at common point.

$$I_D = \frac{1}{2} k'_p \frac{W}{L} (V_{GS} - V_t)^2 (1 + \lambda V_{DS})$$

$$k'_p = \mu_p \frac{\epsilon_{ox}}{t_{ox}}$$

$$V_{GS} < V_t$$

$$V_{DS} \leq V_{GS} - V_t$$



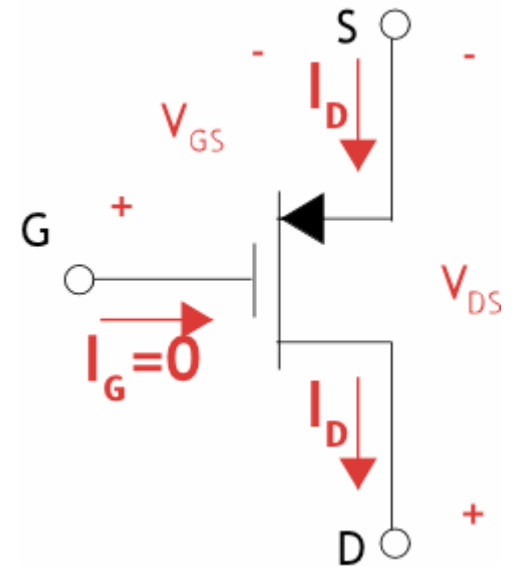
Summary of pMOS FET I-V Characteristics

Cutoff: $V_{GS} > V_t$ $I_D = 0$

Triode: $V_{GS} < V_t$ $I_D = k'_p \frac{W}{L} \left[(V_{GS} - V_t) V_{DS} - \frac{1}{2} V_{DS}^2 \right]$
 $V_{DS} > V_{GS} - V_t$

Saturation: $V_{GS} < V_t$ $I_D = \frac{1}{2} k'_p \frac{W}{L} (V_{GS} - V_t)^2 (1 + \lambda V_{DS})$
 $V_{DS} < V_{GS} - V_t$

Body effect: $|V_t| = |V_{t0}| + \gamma \left(\sqrt{2\phi_f + |V_{SB}|} - \sqrt{2\phi_f} \right)$



Note: V_{GS} , V_{DS} , V_{SB} , V_t , λ , are all **NEGATIVE**